



Form Type	Distribute	Version	2.0	Ref	IPC 1752A	Sectionals	Manufacturing Info/ Material Info	Subsectionals	D, A
Supplier Information									
Company Name	TE Connectivity	Request Document ID		Contact Name	Chan, Nelson	Contact Title	Manager Sales, HKG SELL DIR-EMS		
Company Unique ID	TE Connectivity	Response Date	2015-11-13	Contact Email	nelson.chan@te.com				
Contact Phone Number	+852-2738-8751								
Legal Statement									
Supplier Acceptance	true								
Legal Statement									
The information provided in this document is based upon reasonable inquiry of our suppliers. This information is subject to change. This information does not in any way modify existing purchase specifications or existing contractual or other agreements terms between TE Connectivity (or its affiliated companies) and its customers.									
Product									
Manufacturer Item number	5-104655-5	Amount	1276.2039	Version	-	Identity			
Manufacturer Item Name	40 50/50 HDR DRST SFMNT TIN	Weight Uom	mg	Mfr Site		Authority			
Date		UOM	Each						
EUroHS-0508	Product(s) meets EU RoHS requirement without any exemptions								
ChinaRoHS-0508	Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products								
EUREACH-1214	REACH Candidate Substances of Very High Concern ARE NOT Contained in the Product Above the Limits per the Definition within REACH								
Manufacturing Information									
J-STD-020 MSL Rating		Max Total a Wave Time		Ramp Rate		Wave Additional Info			
Classification Temp		Max Wave Solder Time	20.0	Ramp Down Rate		Psi Rating Reflow			
Max Time Within 5		Psi Rating Wave		Package Designator		Size	0.0		
Time Above 217		Reflow Additional Info		Preheat Max Temp		Terminal Base Alloy	NAC		
Preheat Duration		bulk Solder Termination	NAC	Nbr or Reflow Cycles		Terminal Plating	NAC		
Preheat Min Temp		Nbr of Instances	0	Component Temp Spike		Shape	NAC		
Product Disclosure									
Sub-Item/Material/Substance	Level	Name	Substance Category	Substance CAS	Substance Concentration	Quantity	Mass per Unit	UOM	Exemption
Sub-Item	1	50/50 GRID STND HLDWN PLTD				2.0	29.255	mg	
Material	2	Beryllium Copper				2.0	28.637	mg	
Substance	3	Beryllium	Supplier	7440-41-7	2.0	2.0	0.57274	mg	
Substance	3	Arsenic	Supplier	7440-38-2	0.01	2.0	0.0028637	mg	
Substance	3	Manganese	Supplier	7439-96-5	0.02	2.0	0.0057274	mg	
Substance	3	Cobalt	Supplier	7440-48-4	0.2	2.0	0.057274	mg	
Substance	3	Silicon	Supplier	7440-21-3	0.2	2.0	0.057274	mg	
Substance	3	Iron	Supplier	7439-89-6	0.4	2.0	0.11455	mg	
Substance	3	Antimony	Supplier	7440-36-0	0.01	2.0	0.0028637	mg	
Substance	3	Aluminum	Supplier	7429-90-5	0.2	2.0	0.057274	mg	
Substance	3	Chromium	Supplier	7440-47-3	0.0010	2.0	2.8637E-4	mg	
Substance	3	Copper	Supplier	7440-50-8	96.649	2.0	27.67737	mg	
Substance	3	Lead	Lead/Lead Compounds	7439-92-1	0.1	2.0	0.028637	mg	
Substance	3	Nickel	Nickel	7440-02-0	0.2	2.0	0.057274	mg	
Substance	3	Cadmium	Cadmium/Cadmium Compounds	7440-43-9	0.0050	2.0	0.00143185	mg	
Substance	3	Mercury	Mercury/Mercury Compounds	7439-97-6	5.0E-4	2.0	1.4318E-4	mg	
Material	2	Nickel Plate				2.0	0.234	mg	
Substance	3	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.2	2.0	4.68E-4	mg	
Substance	3	Lead	Lead/Lead Compounds	7439-92-1	0.1	2.0	2.34E-4	mg	

Substance	3	Nickel	Nickel	7440-02-0	99.7	2.0	0.2333	mg	
Material	2	Tin Plate				2.0	0.384	mg	
Substance	3	Tin	Supplier	7440-31-5	99.73	2.0	0.38296	mg	
Substance	3	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.2	2.0	7.68E-4	mg	
Substance	3	Lead	Lead/Lead Compounds	7439-92-1	0.07	2.0	2.688E-4	mg	
Sub-Item	1	50/50 GRID BAND W/PST 30DPL SN				40.0	12.929	mg	
Material	2	Nickel Plate				40.0	0.173	mg	
Substance	3	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.2	40.0	3.46E-4	mg	
Substance	3	Lead	Lead/Lead Compounds	7439-92-1	0.1	40.0	1.73E-4	mg	
Substance	3	Nickel	Nickel	7440-02-0	99.7	40.0	0.17248	mg	
Material	2	Gold Plate				40.0	0.136	mg	
Substance	3	Gold	Supplier	7440-57-5	99.7	40.0	0.13559	mg	
Substance	3	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-0909	0.3	40.0	4.08E-4	mg	
Material	2	Tin Plate				40.0	0.12	mg	
Substance	3	Lead	Lead/Lead Compounds	7439-92-1	0.0999	40.0	1.1988E-4	mg	
Substance	3	Tin	Supplier	7440-31-5	99.9001	40.0	0.11988	mg	
Material	2	Phos Bronze				40.0	12.5	mg	
Substance	3	Beryllium	Supplier	7440-41-7	0.0010	40.0	1.25E-4	mg	
Substance	3	Arsenic	Supplier	7440-38-2	0.015	40.0	0.001875	mg	
Substance	3	Manganese	Supplier	7439-96-5	0.02	40.0	0.0025	mg	
Substance	3	Phosphorus	Supplier	7723-14-0	0.35	40.0	0.04375	mg	
Substance	3	Antimony	Supplier	7440-36-0	0.01	40.0	0.00125	mg	
Substance	3	Tin	Supplier	7440-31-5	5.8	40.0	0.725	mg	
Substance	3	Cobalt	Supplier	7440-48-4	0.1	40.0	0.0125	mg	
Substance	3	Zinc	Supplier	7440-66-6	0.3	40.0	0.0375	mg	
Substance	3	Copper	Supplier	7440-50-8	93.1335	40.0	11.64169	mg	
Substance	3	Chromium	Supplier	7440-47-3	0.01	40.0	0.00125	mg	
Substance	3	Iron	Supplier	7439-89-6	0.1	40.0	0.0125	mg	
Substance	3	Nickel	Nickel	7440-02-0	0.1	40.0	0.0125	mg	
Substance	3	Cadmium	Cadmium/Cadmium Compounds	7440-43-9	0.01	40.0	0.00125	mg	
Substance	3	Mercury	Mercury/Mercury Compounds	7439-97-6	5.0E-4	40.0	6.25E-5	mg	
Substance	3	Lead	Lead/Lead Compounds	7439-92-1	0.05	40.0	0.00625	mg	
Sub-Item	1	40 50/50 GRID HDR HSG .250				1.0	700.5339	mg	
Material	2	LCP-GF35				1.0	700.5339	mg	
Substance	3	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	2.0	1.0	14.01068	mg	
Substance	3	Glass, oxide, chemicals	Supplier	65997-17-3	34.3	1.0	240.28313	mg	
Substance	3	1,3-Benzenedicarboxylic acid, polymer with 1,4-benzenedicarboxylic acid, [1,1-biphenyl]-4,4-diol and 4-hydroxybenzoic acid	Supplier	60088-52-0	62.7	1.0	439.23476	mg	
Substance	3	Carbon black	Supplier	1333-86-4	1.0	1.0	7.00534	mg	